



PRODUCT/PROCESS CHANGE NOTIFICATION

PCN APM-PWR/07/2615
Notification Date 06/11/2007

SILICON LINE CHANGE FOR BIPOLAR DEVICES - BD01 PRODUCT LINE

PWR - PWR BIP/ IGBT/ RF

Table 1. Change Identification

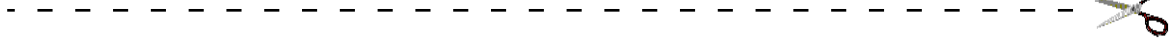
Product Identification (Product Family/Commercial Product)	See attached list
Type of change	Waferfab process change
Reason for change	Production Optimization
Description of the change	Planar Base Island technology is ready to replace the mature Epibase technology in order to align our products to the actual Market. The line BD01 will replace the old ones B904. Feature: Improved hFE linearity and Higher fT frequency benefit: Better performances in switching and linear application.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	See "N" in additional info on P/N
Manufacturing Location(s)	

Table 2. Change Implementation Schedule

Forecasted implementation date for change	06-Sep-2007
Forecasted availability date of samples for customer	04-Jun-2007
Forecasted date for STMicroelectronics change Qualification Plan results availability	04-Jun-2007
Estimated date of changed product first shipment	10-Sep-2007

Table 3. List of Attachments

Customer Part numbers list	
Qualification Plan results	



Customer Acknowledgement of Receipt		PCN APM-PWR/07/2615				
Please sign and return to STMicroelectronics Sales Office		Notification Date 06/11/2007				
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td style="padding: 2px;">Name:</td></tr> <tr><td style="padding: 2px;">Title:</td></tr> <tr><td style="padding: 2px;">Company:</td></tr> <tr><td style="padding: 2px;">Date:</td></tr> <tr><td style="padding: 2px;">Signature:</td></tr> </table>	Name:	Title:	Company:	Date:	Signature:
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DOCUMENT APPROVAL

Name	Function
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Porto, Michele Claudio	Division Product Manager
Falcone, Giuseppe	Division Q.A. Manager

	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Reliability evaluation

on

**BD01 for silicon line change on
TIP127 and MJD127T4 sales type**

ISSUED BY	RELIABILITY DEPARTMENT	Page 1 of 10
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	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Table of Contents

1.	Introduction	pg. 3
2.	Test vehicles	pg. 4
3.	Failure Criteria	pg. 5
4.	Evaluation plan and results	pg. 6
5.	Appendixes	
	- Technological Characteristics	pg. 8
	- Reliability Test Description	pg. 10

	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Introduction

This report is aimed to qualify the new line BD01 for line change on devices TIP127 and MJD127T4

The Qualification Reliability test trials have been performed in ST Catania Site.

The evaluation results meet ST products qualification targets, therefore the new line BD01 for silicon line change on TIP127 and MJD127T4 is qualified.

ISSUED BY	RELIABILITY DEPARTMENT	Page 3 of 10
------------------	-----------------------------------	---------------------

	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Test Vehicles :

Product Line	Sales Type	Package
BD01	TIP127	TO-220
BD01	MJD127T4	DPAK

ISSUED BY	RELIABILITY DEPARTMENT	Page 4 of 10
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	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Failure Criteria :

A failed component is a device which becomes inoperative during the test or it fails on meeting the end limits foreseen in the device specification, for one or more than the parameters here below reported

Parameter Power BIPOLAR Main Parameter

Collector Leakage Current (Icbo or Iceo or Ices, etc...)
 Emitter Leakage (Iebo)
 H_{FE} , Vcesat, Vbesat, Vf
 Breakdown Voltage (BVcbo, BVceo, Vbces, Bvebo)

ISSUED BY	RELIABILITY DEPARTMENT	Page 5 of 10
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	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Reliability Evaluation Plan and results

D.U.T.: TIP127 LINE: BD01 PACKAGE: TO-220

Test	Conditions	S.S.	Requirement	Results
H.T.S.	TA=150°C	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	TA=85°C - RH=85% Vbias= 50V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.R.B.	T.A.=150°C Vdd=80V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	TA=121°C - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at 96 hours.
THERMAL CYCLES AIR TO AIR	TA=-65°C TO 150°C 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cy
THERMAL FATIGUE	ΔTC=105°C - Pd=4.8W	77 x 1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.

ISSUED BY	RELIABILITY DEPARTMENT	Page 6 of 10
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	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Reliability Evaluation Plan and results

D.U.T.: MDJ127T4 LINE: BD01 PACKAGE: DPAK

Test	Conditions	S.S.	Requirement	Results
PRECONDITIONING OF SMD DEVICES BEFORE TC/THB/ENV. SEQ.	DRYNG 1H @ 125°C STORE 168H @ TA=85°C RH=85% Reflow @ 260°C 3 times	204 x 1 Lot	Parameter deviation within spec. limits at end of preconditioning.	No parameter deviation out of spec. limits at end of preconditioning.
H.T.S.	TA=150°C	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
T.H.B.	<i>D.U.T. SMD PRECONDITIONED</i> TA=85°C - RH=85% Vbias= 50V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
H.T.R.B.	T.A.=150°C Vdd=80V	77 x 1 Lot	Parameter deviation within spec. limits at 1000 hours.	No parameter deviation out of spec. limits at 1000 hours.
PRESSURE POT	TA=121°C - PA=2Atm	77 x 1 Lot	Parameter deviation within spec. limits at 96 hours.	No parameter deviation out of spec. limits at 96 hours.
THERMAL CYCLES AIR TO AIR	<i>D.U.T. SMD PRECONDITIONED</i> TA=-65°C TO 150°C 1 HOUR / CYCLE	77 x 1 Lot	Parameter deviation within spec. limits at 500 cycles.	No parameter deviation out of spec. limits at 500 cy
THERMAL FATIGUE	ΔTC=105°C - Pd=2W	77 x 1 Lot	Parameter deviation within spec. limits at 10k cycles.	No parameter deviation out of spec. limits at 10Kcy.
ENVIRONMENTAL SEQUENCE	<i>D.U.T. SMD PRECONDITIONED</i> 100 THERMAL CYCLES + 96H PP	50 x 1 Lot	Parameter deviation within spec. limits at end of test.	No parameter deviation out of spec. limits at end of test.

ISSUED BY	RELIABILITY DEPARTMENT	Page 7 of 10
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	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Technological Characteristics

D.U.T.: TIP127 LINE: BD01 PACKAGE: TO-220

DIE	<i>Technology:</i> PLANAR PNP		<i>Passivation :</i> P-Vapox	
	<i>Material:</i> Silicon		<i>Dimensions :</i> 1830 x 1970 um	
DIE ATTACH	Soft Solder	FRAME	<i>Frame and lead material:</i>	Raw Copper
			<i>Frame coating :</i>	Full Ni/NiP
WIRE BOND	Ultrasonic	WIRE	<i>Material :</i>	Al/Mg Base Al/Mg Emitter
			<i>Diameter :</i>	5 mils Base 7 mils Emitter
SEALING	Molding	PACKAGING	<i>Material :</i>	Epoxy Resin

PRODUCTION PLACES: WAFER PROCESSING: SINGAPORE
ASSEMBLY LOCATION: AIN SEBAA; SHENZHEN
QA LOCATION: AIN SEBAA; SHENZHEN

ISSUED BY	RELIABILITY DEPARTMENT	Page 8 of 10
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	APM CATANIA RELIABILITY REPORT	Date: Mar '07
		No 08/07

Technological Characteristics

D.U.T.: MDJ127T4 LINE: BD01 PACKAGE: DPAK

DIE	<i>Technology:</i> PLANAR PNP <i>Material:</i> Silicon <i>Passivation :</i> P-Vapox <i>Metallization – Front :</i> Al/Si <i>Dimensions :</i> 1830 x 1970 um <i>- Back :</i> Au/Cr/Ni/Au			
	DIE ATTACH	Soft Solder	FRAME	<i>Frame and lead material:</i> <i>Frame coating :</i> <i>Lead coating :</i>
WIRE BOND	Ultrasonic	WIRE	<i>Material :</i> <i>Diameter :</i>	Al/Mg Base Al/Mg Emitter 5 mils Base 7 mils Emitter
SEALING	Molding	PACKAGING	<i>Material :</i>	Epoxy Resin

PRODUCTION PLACES: WAFER PROCESSING: SINGAPORE
 ASSEMBLY LOCATION: AIN SEBAA; SHENZHEN
 QA LOCATION: AIN SEBAA; SHENZHEN

ISSUED BY	RELIABILITY DEPARTMENT	Page 9 of 10
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	APM CATANIA RELIABILITY REPORT	Date:	Mar '07
		No	08/07

Reliability Test Description

High Temperature Reverse Bias (HTRB)

This test is performed in order to demonstrate the quality and reliability of devices subjected to an elevated temperature and simultaneously reverse biased. The purpose of this test is to detect surface defects such as poor passivation, presence of contaminants, etc...

High Temperature Storage (HTS)

This stress test is performed to check the device life in a high temperature ambient. Specimens are put for a period of time inside a stove in free air. Detectable failure mechanisms are presence of contaminants and metal corrosion.

Temperature Humidity Bias (THB)

This test is performed to check the device life in a high humidity ambient. Specimens are subjected to a permanent bias in a climatic chamber in the presence of steam. Detectable failure mechanisms are metal corrosion and molding defects.

Pressure Pot

This test is performed in order to check device life in a high humidity ambient in an accelerated way. Specimens are subjected for a period of time inside an autoclave in the presence of steam and pressure. Detectable failure mechanism is metal corrosion.

Thermal Fatigue

This test is performed to demonstrate the quality and reliability of devices exposed to cyclic variation in electrical stress between "on" and "off" conditions and resultant cyclic variation in device and case temperatures (thermo-mechanical stress). The purpose of this test is to detect assembly defects: improper die-attach, bonding weakness and thermal mismatch among various components of the package.

ISSUED BY	RELIABILITY DEPARTMENT	Page 10 of 10
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